



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification#20171108001
Datasheet for WL1801MOD, WL1805MOD, WL1831MOD, WL1835MOD
Information Only

Date: November 28, 2017
To: PREMIER FARNELL PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
WL1801MODGBMOCT	null
WL1831MODGBMOCT	null
WL1835MODGBMOCR	null
WL1835MODGBMOCT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20171108001	PCN Date:	November 28, 2017
Title:	Datasheet for WL1801MOD, WL1805MOD, WL1831MOD, WL1835MOD□		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



WL1801MOD, WL1805MOD, WL1831MOD, WL1835MOD

SWRS152L – JULY 2013 – REVISED DECEMBER 2015

Changes from Revision K (November 2014) to Revision L

Page

• Changed Features section	<u>1</u>
• Changed Section 1.3, Description	<u>2</u>
• Added support at 802.11 g/n to note 1 in Table 3-1	<u>5</u>
• Changed to reflect correct corner pin marking in Figure 4-1 and Figure 4-2	<u>6</u>
• Changed pin 64 to GND in Table 4-1	<u>8</u>
• Changed description for pin 14 (WL_IRQ_1V8) in Table 4-1	<u>8</u>
• Changed description of WL_IRQ_1V8 in Table 4-1	<u>9</u>
• Added storage temperature to Section 5.1, Absolute Maximum Ratings	<u>11</u>
• Added Section 5.2, ESD Ratings (removed Handling Ratings table)	<u>11</u>
• Added TYP values for VBAT, VIO in Section 5.4, Recommended Operating Conditions	<u>12</u>
• Added VIO parameter in Section 5.4, Recommended Operating Conditions	<u>12</u>
• Changed Section 5.6, Thermal Characteristics	<u>12</u>
• Changed parameter heading from "2G4_ANT2_W + 2G4_ANT1_WB Pins" in Section 5.8, WLAN Performance: 2.4-GHz Transmitter Power	<u>14</u>
• Added note on maximum transmitter power degradation and changed note on regulatory constraints in Section 5.8, WLAN Performance: 2.4-GHz Transmitter Power	<u>14</u>
• Added note 1 in Section 5.10, Bluetooth Performance: BR, EDR Receiver Characteristics—In-Band Signals	<u>15</u>
• Added note 1 in Section 5.11, Bluetooth Transmitter, BR	<u>16</u>
• Changed note 3 from "Assumes VBAT ADC measurement accuracy of 5%" in Section 5.11, Bluetooth Transmitter, BR	<u>16</u>
• Changed BR RF output power from 12.7 dBm typical in Section 5.11, Bluetooth Performance: Transmitter, BR ...	<u>16</u>

• Added note 1 in Section 5.11, Bluetooth Transmitter, BR	16
• Changed note 3 from "Assumes VBAT ADC measurement accuracy of 5%" in Section 5.12, Bluetooth Transmitter, EDR	16
• Added note 1 in Section 5.13, Bluetooth Performance: Modulation, BR	17
• Added note 1 in Section 5.14, Bluetooth Performance: Modulation, EDR	17
• Added note 1 in Section 5.15, Bluetooth LE Performance: Receiver Characteristics – In-Band Signals	17
• Changed note 3 from "Assumes VBAT ADC measurement accuracy of 5%"	18
• Changed Bluetooth LE RF transmitter output power from 10.0 dBm typical (VBAT ≥ 3V) and 7.2 dBm (VBAT ≤ 3V) in Section 5.16, Bluetooth LE Performance: Transmitter Characteristics	18
• Added note 1 through note 3 in Section 5.16, Bluetooth LE Performance: Transmitter Characteristics	18
• Deleted note: "To reduce the maximum BLE power, use a VS command. The optional extra margin is offered to compensate for design losses, such as trace and filter losses, and to achieve the maximum allowed output power at system level." in Section 5.16, Bluetooth LE Performance: Transmitter Characteristics	18
• Added note 1 in Section 5.17, Bluetooth LE Performance: Modulation Characteristics	18
• Changed BR power from 12.7 dBm in Section 5.18, Bluetooth-BLE Dynamic Currents	18
• Added power supply current of VIO 60 µA for WLAN and Bluetooth sleep modes in Table 6-3	29
• Changed from Bluetooth 4.0 in Section 6.2, Bluetooth	29
• Changed reference design from WL1835MODB in Section 7.1.1, Typical Application – WL1835MODGB	31
• Changed Figure 7-1	31
• Changed BOM in Table 7-1 Section 7.1.1, Typical Application – WL1835MODGB	32
• Added note in Section 7.1.3, RF Trace and Antenna Layout Recommendations	33
• Changed board name from TMDXWL1835MODCOM8B in Figure 7-2	33
• Changed note in Section 7.1.6.2, SMT Recommendations	36
• Changed corner marking from pin 1 in Figure 9-1	39
• Added module weight in Section 9.1, Mechanical Packaging and Orderable Information	39
• Added Section 9.2, Tape and Reel Information	40

The datasheet number will be changing.

Device Family	Change From:	Change To:
WL1801MOD, WL1805MOD, WL1831MOD, WL1835MOD□	SWRS152M	SWRS152L

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/WL1801MOD>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

WL1801MODGBMOCR	WL1801MODGBMOCT	WL1805MODGBMOCR	WL1805MODGBMOCT
WL1831MODGBMOCR	WL1831MODGBMOCT	WL1835MODGBMOCR	WL1835MODGBMOCT

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com